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**NOH et al.**(10) **Pub. No.: US 2023/0230944 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SEMICONDUCTOR PACKAGE**(71) Applicant: **SAMSUNG ELECTRONICS CO., LTD.**, Suwon-si (KR)(72) Inventors: **Boin NOH**, Suwon-si (KR); **Jeong Hoon AHN**, Seongnam-si (KR); **Yun Ki CHOI**, Yongin-si (KR)(21) Appl. No.: **17/959,352**(22) Filed: **Oct. 4, 2022**(30) **Foreign Application Priority Data**

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(57)

**ABSTRACT**

A semiconductor package includes a second semiconductor chip disposed on a first semiconductor chip. The first semiconductor chip includes a first semiconductor substrate, a through via, and a lower pad disposed on the through via. The lower pad includes a first segment and a second segment connected thereto. The first segment overlaps the through via. The second segment is disposed on an edge region of the first segment. The second segment has an annular shape. The second semiconductor chip includes a second semiconductor substrate, an upper pad disposed on a bottom surface of the second semiconductor substrate, and a connection terminal disposed between the upper pad and lower pads. The second segment at least partially surrounds a lateral surface of the upper pad. A level of a top surface of the second segment is higher than that of an uppermost portion of the connection terminal.

